

Datasheet revision 1.3

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Tack Flux No-Clean for Low Temp in Jar 150g

Product Highlights

Ideal for all rework, solder, de-solder and reflow applications Non-corrosive, non-conductive, no-clean Tack flux will not run all over PCB when applied Has a pleasant odor Excellent wetting Easily cleaned with isopropyl alcohol (IPA) Attachment of BGA spheres Soldering flip chip components Long stencil life Wide process window Clear residue Commonly used with Sn42/Bi58, Sn42/Bi57.6/Ag0.4, and Sn42/Bi57/Ag1 alloys, which melt at 138°C (281°F) **RoHS 3 and REACH compliant**



Specifications

Flux Type: Flux Classification: Flux Activation Temperature: Packaging: Shelf Life: Synthetic No-Clean (for low temperature applications) REL0 100°C (212°F) Jar 150g Refrigerated >24 months, Unrefrigerated >24 months

Stencil Life >8 hours @ 20-50% RH 22-28°C (72-82°F) >4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Do not freeze. Allow 4 hours for flux to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Conforms to the following Industry Standards: J-STD-004B, Amendment 1 (Solder Fluxes): RoHS 3 Directive (EU) 2015/863:

Yes Yes